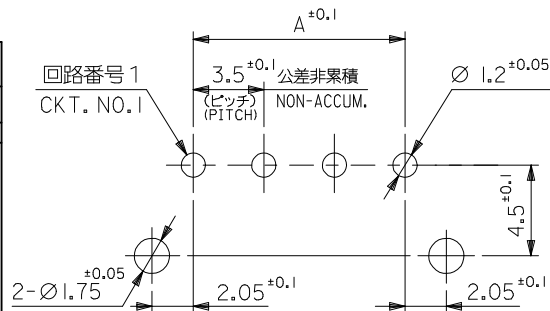
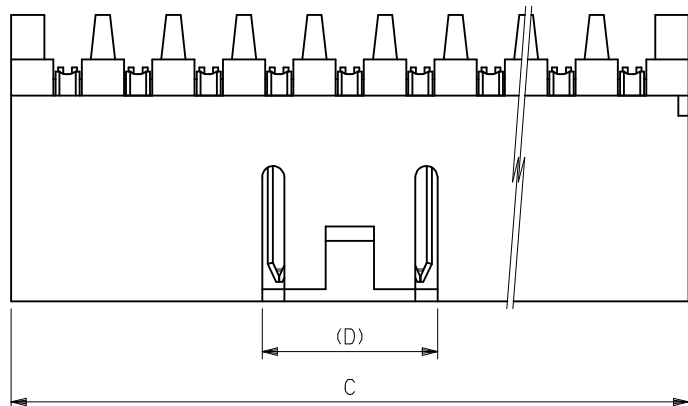
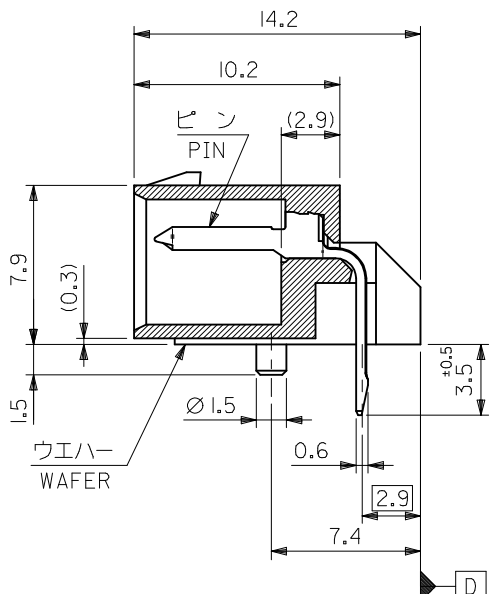
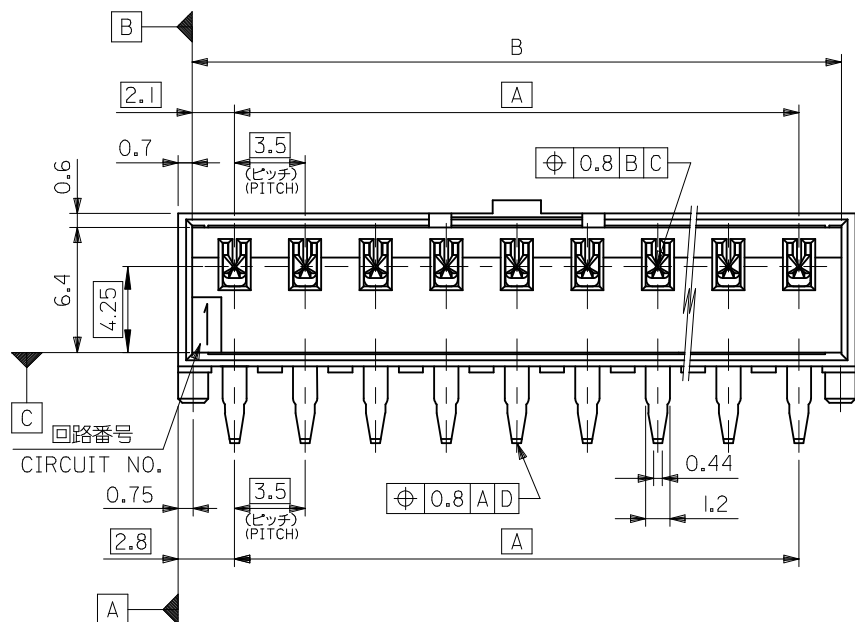




基板取付穴推奨寸法 (参考) (t = 1.6)
RECOMMENDED P.C. BOARD HOLE DIM. (REF.)

注記 NOTES

1. 嵌合相手 : 51067 シリーズ
MATE WITH : 51067 SERIES
2. 材質
MATERIAL
ウエハー : PBTP (ガラス15%入り) 、UL94V-0
WAFER : PBTP (G.F 15%) ,UL94V-0
ピン : 黄銅、ニッケル下地 鍍メッキ (t=0.254)
PIN : BRASS
TIN OVER NICKEL PLATING (t=0.254)
3. 本製品は 53259- **20 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53259- **20.
4. メッキ仕様
TERMINAL PLATING
表面メッキ : スズメッキ 1μm MIN.
SURFACE PLATE : TIN 1μm MIN.
下地メッキ : ニッケルメッキ 1μm MIN.
UNDER PLATE : NICKEL 1μm MIN.



8.7	54.6	53.2	49.0	53259-1529	15
└	51.1	49.7	45.5	-1429	14
	47.6	46.2	42.0	-1329	13
	44.1	42.7	38.5	-1229	12
	40.6	39.2	35.0	-1129	11
	37.1	35.7	31.5	-1029	10
	33.6	32.2	28.0	-0929	9
	30.1	28.7	24.5	-0829	8
	26.6	25.2	21.0	-0729	7
└	23.1	21.7	17.5	-0629	6
	19.6	18.2	14.0	-0529	5
8.7	16.1	14.7	10.5	-0429	4
6.1	12.6	11.2	7.0	-0329	3
6.1	9.1	7.7	3.5	53259-0229	2
(D)	C	B	A	TRAY PACKAGE	CKT. 極数
				ORDER No. オーダー番号	

REVISED EC NO: J2009-1054 2009/02/17 DRWN: MWABE I 2009/02/18 CHKD: HYALIMA 2009/02/18 APPR: NUKITA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY T. UENO	DATE 2004/04/22	TITLE 3.5 W/B CONN W.A. R/A -LEAD FREE- MOLEX INCORPORATED			
		10 OVER 30 UNDER	± 0.25	CHECKED BY M. SASAO	DATE 2004/04/22				
		30 OVER	± 0.3	APPROVED BY M. SASAO	DATE 2004/04/22				
		ANGULAR ±3 °		MATERIAL NO.					DOCUMENT NO.
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-53259-003		1 OF 1		
	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

MATERIAL
材料

注記参照
SEE NOTES